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What is claimed is:

1. A semiconductor device comprising:

an adhesive layer on a substrate;

an insulating film on said adhesive layer; and

light emitting elements on said insulating film,

wherein emitted from said light emitting elements is emitted through said substrate.

- A device according to claim 1, wherein said substrate is a plastic substrate comprising an organic material.
- 3. A device according to claim 1, wherein said semiconductor device further comprises driver circuits on said insulating film, and said light emitting elements and said driver circuits comprise TFTs.
- A device according to claim 1, wherein color filters are provided on said substrate at positions aligned with said light emitting elements.
- 5. A device according to claim 4, wherein said insulating film covers said colorfilters, and is planarized.
 - 6. A device according to claim 4, wherein red color filters of said color filters are provided at positions aligned with at least the channel forming regions of said TFTs.
 - 7. A device according to claim 1, wherein said adhesive layer comprises a

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material selected from the group consisting of polyimide, acrylic, and epoxy resin.

- 8. A device according to claim 1, wherein a fixing substrate is provided over said light emitting element so as to face said substrate.
- A device according to claim 4, further comprising a black mask together with said color filters.
- 10. A device according to claim 1, wherein said semiconductor device is selected from the group consisting of a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, and a personal digital assistant.
 - 11. A semiconductor device comprising:
- a first substrate comprising an organic material and having TFTs provided thereon:
 - a second substrate; and
 - a liquid crystal material retained between said first and second substrates, wherein color filters are provided between said first substrate and said

TFTs.

- 12. A device according to claim 11, wherein said first substrate comprising an organic material is a plastic substrate.
- 13. A device according to claim 11, further comprising an insulating film covering
 said color filters and planarized.

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- 14. A device according to claim 11, wherein said color filters are provided at positions aligned with at least the channel forming regions of said TFTs.
- 15. A device according to claim 11, further comprising a black mask together with
 said color filters.
 - 16. A device according to claim 11, wherein said semiconductor device is selected from the group consisting of a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, and a personal digital assistant.
 - 17. A semiconductor device comprising:

color filters are provided on a substrate;

an adhesive layer over said substrate and said color filters;

an insulating film on said adhesive layer; and

light emitting elements on said insulating film,

wherein emitted from said light emitting elements is emitted through said substrate, and

wherein said substrate is a plastic substrate comprising an organic material.

- 18. A device according to claim 17, wherein said semiconductor device further comprises driver circuits on said insulating film, and said light emitting elements and said driver circuits comprise TFTs.
 - 19. A device according to claim 17, wherein at positions aligned with said light

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emitting elements.

- 20. A device according to claim 17, wherein red color filters of said color filters are provided at positions aligned with at least the channel forming regions of said TFTs
- 21. A device according to claim 17, wherein said adhesive layer comprises a material selected from the group consisting of polyimide, acrylic, and epoxy resin.
- 22. A device according to claim 17, wherein a fixing substrate is provided over said light emitting element so as to face said substrate.
- 23. A device according to claim 17, further comprising a black mask together with said color filters.
- 24. A device according to claim 17, wherein said semiconductor device is selected from the group consisting of a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, and a personal digital assistant.
- 25. A method of manufacturing a semiconductor device comprising the steps of:

forming a separating layer on a first substrate;

forming an insulating film on said separating layer;

forming light emitting elements on said insulating film;

attaching a fixing substrate on said light emitting elements using a first

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adhesive laver:

removing said separating layer by exposing said separating layer to gas containing halogen fluoride to separate said first substrate; and

attaching a second substrate to said insulating film using a second adhesive

wherein said second substrate has color filters provided thereon.

26. A method according to claim 25, wherein said first adhesive layer comprises a material selected from the group consisting of polyimide, acrylic, and epoxy resin.

27. A method according to claim 25, wherein said second adhesive layer comprises a material selected from the group consisting of polyimide, acrylic, and epoxy resin.

28. A method according to claim 25, wherein said second substrate is a plastic substrate.

 A method according to claim 25, wherein said separating layer is a film comprising silicon.

30. A method of manufacturing a semiconductor device comprising the steps of:

forming a separating layer on a first substrate;

forming an insulating film on said separating layer;

forming an active layer, a gate insulating film, and gate electrodes on said

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insulating film;

forming a first interlayer insulating film so as to cover said gate electrodes:

forming wiring and pixel electrodes on said first interlayer insulating film:

attaching a fixing substrate provided with an opposing electrode on said first substrate using a sealant;

injecting liquid crystal between said pixel electrodes and said opposing electrode;

removing said separating layer by exposing said separating layer to gas containing halogen fluoride to separate said first substrate; and

attaching a second substrate to said insulating film using an adhesive layer,

wherein said second substrate has color filters provided thereon.

- 31. A method according to claim 30, wherein said adhesive layer comprises a material selected from the group consisting of polyimide, acrylic, and epoxy resin.
- 32. A method according to claim 30, wherein said color filters are aligned with
 said active layer seen from the side of said second substrate.
 - 33. A method according to claim 30, wherein said color filters are aligned with said active layer are red color filters.
 - 34. A method according to claim 30, wherein said second substrate is a plastic

substrate.

- 35. A method according to claim 30, wherein said fixing substrate is a light transmitting substrate.
- 36. A method according to claim 30, wherein said separating layer is a film comprising silicon.